



PC Board Layout  
Component Side Shown

REVISION RECORD				
REV	ECO	DESCRIPTION	DRAFT	CHKD

#### NOTES:

#### MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE  $\phi 0.45\text{mm}$ .
- 3.PLATING :GOLD PLATING  $\text{Fu} \sim 50\mu$  OVER NICKEL.
- 4.SHIELD :0.20mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

#### ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

#### MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

#### ENVIRONMENTAL:

1. STORAGE : -40°C~+85°C
2. OPERATION : 0° TO 70°

<div> <div>MM</div> <div>INCH</div> </div> <div>TOLERANCES EXCEPT AS NOTED</div> <div> <div>MM</div> <div> <div>0 ± 0.15</div> <div>0.00 ± 0.075</div> <div>0.00 ± 0.05</div> </div> </div> <div>ANGLES ± 0.5</div> <div> <div>THIRD ANGLE PROJECTION</div> </div>	DFTD 黄彬	DATE 2020. 6. 16	<div> <div> <div>韩下</div> <div>HANXIA</div> </div> <div>深圳市韩下电子有限公司</div> </div>	
	CHKD 张伟	DATE 2020. 6. 16		
	MFG	DATE	<div>TITLE</div> <div>HX-RJ45 90° 5631-1x2 8P8C</div>	
	APPL 罗小春	DATE 2020. 6. 16		
	MATERIAL :		<div>DRAWING NO. TESJA1007</div> <div>SIZE A3</div> <div>REV 0</div>	